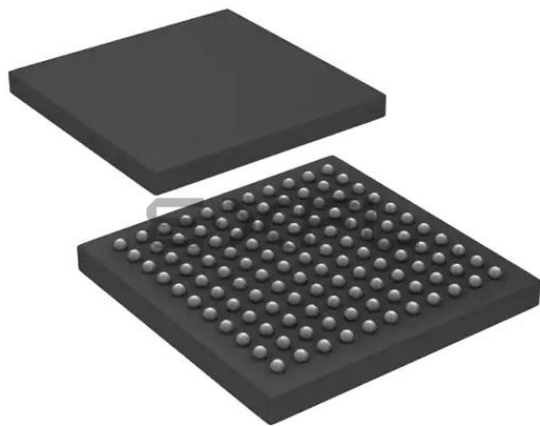




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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx360f512lt-80i-bg

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

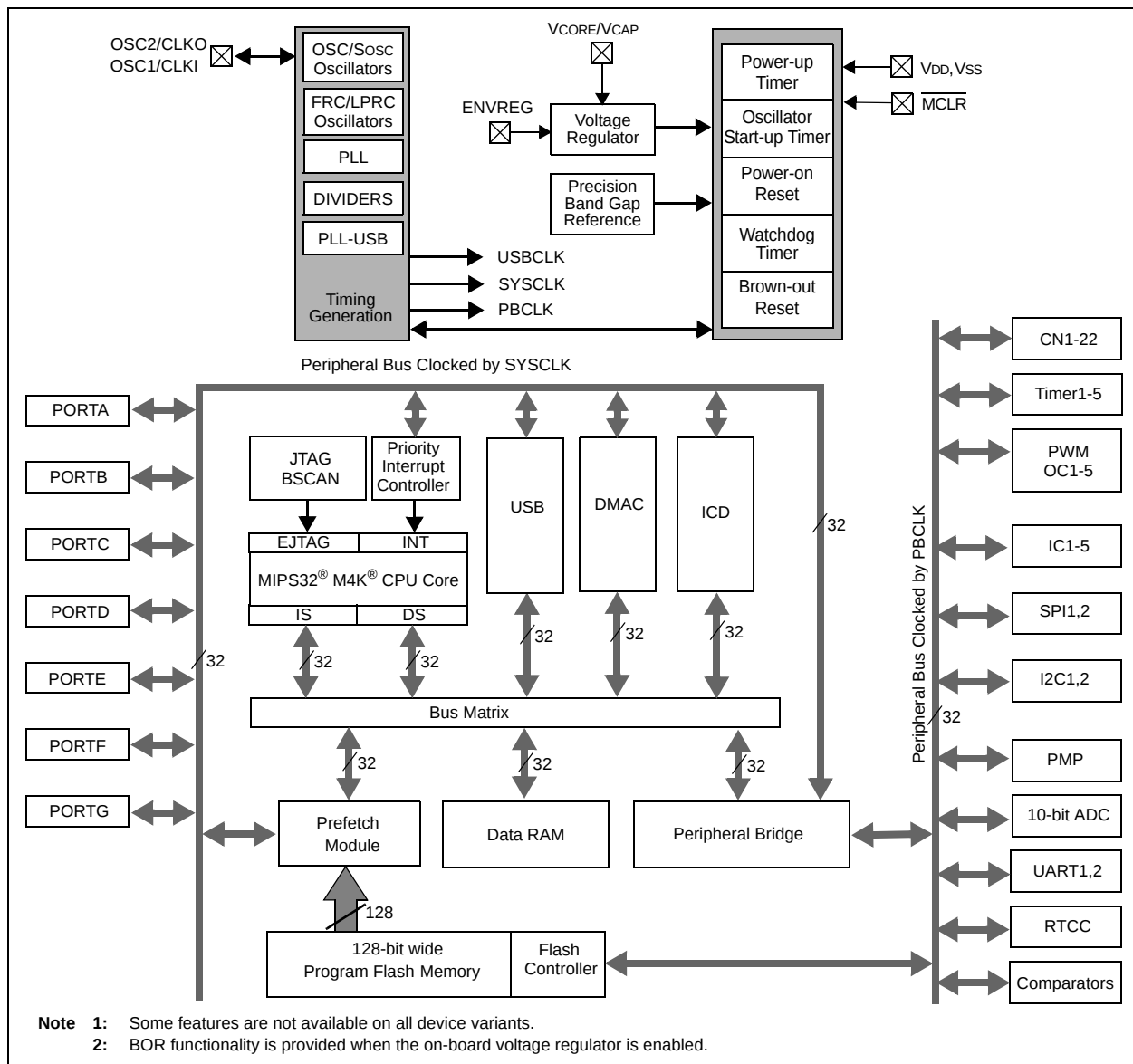
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the PIC32MX3XX/4XX devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX3XX/4XX family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: BLOCK DIAGRAM^(1,2)



PIC32MX3XX/4XX

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number ⁽¹⁾			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
PMD0	60	93	A4	I/O	TTL/ST	Parallel Master Port Data (De-multiplexed Master mode) or Address/Data (Multiplexed Master modes).
PMD1	61	94	B4	I/O	TTL/ST	
PMD2	62	98	B3	I/O	TTL/ST	
PMD3	63	99	A2	I/O	TTL/ST	
PMD4	64	100	A1	I/O	TTL/ST	
PMD5	1	3	D3	I/O	TTL/ST	
PMD6	2	4	C1	I/O	TTL/ST	
PMD7	3	5	D2	I/O	TTL/ST	
PMD8	—	90	A5	I/O	TTL/ST	
PMD9	—	89	E6	I/O	TTL/ST	
PMD10	—	88	A6	I/O	TTL/ST	
PMD11	—	87	B6	I/O	TTL/ST	
PMD12	—	79	A9	I/O	TTL/ST	
PMD13	—	80	D8	I/O	TTL/ST	
PMD14	—	83	D7	I/O	TTL/ST	
PMD15	—	84	C7	I/O	TTL/ST	
PMRD	53	82	B8	O	—	Parallel Master Port Read Strobe.
PMWR	52	81	C8	O	—	Parallel Master Port Write Strobe.
PMALL	30	44	L8	O	—	Parallel Master Port Address Latch Enable low-byte (Multiplexed Master modes).
PMALH	29	43	K7	O	—	Parallel Master Port Address Latch Enable high-byte (Multiplexed Master modes).
VBUS	34	54	H8	I	Analog	USB Bus Power Monitor.
VUSB	35	55	H9	P	—	USB Internal Transceiver Supply. If the USB module is <i>not</i> used, this pin must be connected to VDD.
VBUSON	11	20	H1	O	—	USB Host and OTG Bus Power Control Output.
D+	37	57	H10	I/O	Analog	USB D+.
D-	36	56	J11	I/O	Analog	USB D-.
USBID	33	51	K10	I	ST	USB OTG ID Detect.
ENVREG	57	86	A7	I	ST	Enable for On-Chip Voltage Regulator.
TRCLK	—	91	C5	O	—	Trace Clock.
TRD0	—	97	A3	O	—	Trace Data Bits 0-3.
TRD1	—	96	C3	O	—	
TRD2	—	95	C4	O	—	
TRD3	—	92	B5	O	—	
PGED1	16	25	K2	I/O	ST	Data I/O pin for programming/debugging communication channel 1.
PGEC1	15	24	K1	I	ST	Clock input pin for programming/debugging communication channel 1.

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer

Analog = Analog input
O = Output

P = Power
I = Input

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.

TABLE 4-3: INTERRUPT REGISTERS MAP FOR PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX340F128L, PIC32MX360F256L AND PIC32MX360F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88..#)	Register Name	Bit Range	Bits																All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0		
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000	
		15:0	—	—	—	MVEC	—	TPC<2:0>				—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	SRIPL<2:0>				—	—	VEC<5:0>					0000	
1020	IPTMR	31:16	IPTMR<31:0>																0000	
		15:0																	0000	
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1RXIF	SPI1TXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000	
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000	
1040	IFS1	31:16	—	—	—	—	—	—	—	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000	
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000	
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1RXIE	SPI1TXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000	
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000	
1070	IEC1	31:16	—	—	—	—	—	—	—	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000	
		15:0	RTCCIE	FSCMIE	I2C2MIE	—	—	—	—	—	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000	
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	SPI1IP<2:0>			SPI1IS<1:0>			—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>			—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>			—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-7: TIMER1-5 REGISTERS MAP⁽¹⁾

Virtual Address (BF80-#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0600	T1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	TWDIS	TWIP	—	—	—	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—	0000
0610	TMR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR1<15:0>																0000
0620	PR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR1<15:0>																FFFF
0800	T2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>		—	T32	—	TCS ⁽²⁾	—	0000
0810	TMR2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR2<15:0>																0000
0820	PR2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR2<15:0>																FFFF
0A00	T3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>		—	—	—	TCS ⁽²⁾	—	0000
0A10	TMR3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR3<15:0>																0000
0A20	PR3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR3<15:0>																FFFF
0C00	T4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>		—	T32	—	TCS ⁽²⁾	—	0000
0C10	TMR4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR4<15:0>																0000
0C20	PR4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR4<15:0>																FFFF
0E00	T5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>		—	—	—	TCS ⁽²⁾	—	0000
0E10	TMR5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR5<15:0>																0000
0E20	PR5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR5<15:0>																FFFF

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note 1:** All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.
- 2:** This bit is not available on 64-pin devices.

TABLE 4-9: OUTPUT COMPARE1-5 REGISTERS MAP⁽¹⁾

Virtual Address (BF80-#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																XXXX
		15:0																	XXXX
3020	OC1RS	31:16	OC1RS<31:0>																XXXX
		15:0																	XXXX
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																XXXX
		15:0																	XXXX
3220	OC2RS	31:16	OC2RS<31:0>																XXXX
		15:0																	XXXX
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																XXXX
		15:0																	XXXX
3420	OC3RS	31:16	OC3RS<31:0>																XXXX
		15:0																	XXXX
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																XXXX
		15:0																	XXXX
3620	OC4RS	31:16	OC4RS<31:0>																XXXX
		15:0																	XXXX
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																XXXX
		15:0																	XXXX
3820	OC5RS	31:16	OC5RS<31:0>																XXXX
		15:0																	XXXX

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-31: PORTF REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H AND PIC32MX340F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	07FF
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-32: PORTF REGISTERS MAP FOR PIC32MX420F032H, PIC32MX440F128H AND PIC2MX440F256H DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	03FF
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-43: USB REGISTERS MAP⁽¹⁾

Virtual Address (BF88-#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5040	U1OTG IR ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
		15:0	—	—	—	—	—	—	—	—	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF	0000
5050	U1OTG IE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	IDIE	T1MSECIE	LSTATEIE	ACTVIE	SESVDIE	SESENDIE	—	VBUSVDIE	0000
5060	U1OTG STAT ⁽³⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD	0000
5070	U1OTG CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	DPPULUP	DMPULUP	DPPULDWN	DMPULDWN	VBUSON	OTGEN	VBUSCHG	VBUSDIS	0000
5080	U1PWRC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	UACTPND ⁽⁴⁾	—	—	USLPGRD	—	—	USUSPEND	USBPWR	0000
5200	U1IR ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIF	ATTACHIF	RESUMEIF	IDLEIF	TRNIF	SOFIF	UERRIF	URSTIF DETACHIF	0000 0000
5210	U1IE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	STALLIE	ATTACHIE	RESUMEIE	IDLEIE	TRNIE	SOFIE	UERRIE	URSTIE DETACHIE	0000 0000
5220	U1EIR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEF	BMXEF	DMAEF	BTOEF	DFN8EF	CRC16EF	CRC5EF EOFEF	PIDEF	0000 0000
5230	U1EIE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BTSEE	BMXEE	DMAEE	BTOEE	DFN8EE	CRC16EE	CRC5EE EOFEE	PIDEE	0000 0000
5240	U1STAT ⁽³⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ENDPT<3:0> ⁽⁴⁾				DIR	PPBI	—	—	0000
5250	U1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	JSTATE ⁽⁴⁾	SE0 ⁽⁴⁾	PKTDIS TOKBUSY	USBRST	HOSTEN	RESUME	PPBRST	USBEN SOFEN	0000 0000
5260	U1ADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LSPDEN	DEVADDR<6:0>							0000
5270	U1BDTP1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRL<7:1>							—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note 1:** Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.
- 2:** This register does not have associated CLR, SET, and INV registers.
- 3:** All bits in this register are read-only; therefore, CLR, SET, and INV registers are not supported.
- 4:** The reset value for this bit is undefined.

14.0 TIMER2/3 AND TIMER4/5

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. “Timers”** (DS61105) of the *“PIC32 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

This family of PIC32MX devices features four synchronous 16-bit timers (default) that can operate as a free-running interval timer for various timing applications and counting external events. The following modes are supported:

- Synchronous Internal 16-bit Timer
- Synchronous Internal 16-bit Gated Timer
- Synchronous External 16-bit Timer

Two 32-bit synchronous timers are available by combining Timer2 with Timer3 and Timer4 with Timer5. The 32-bit timers can operate in three modes:

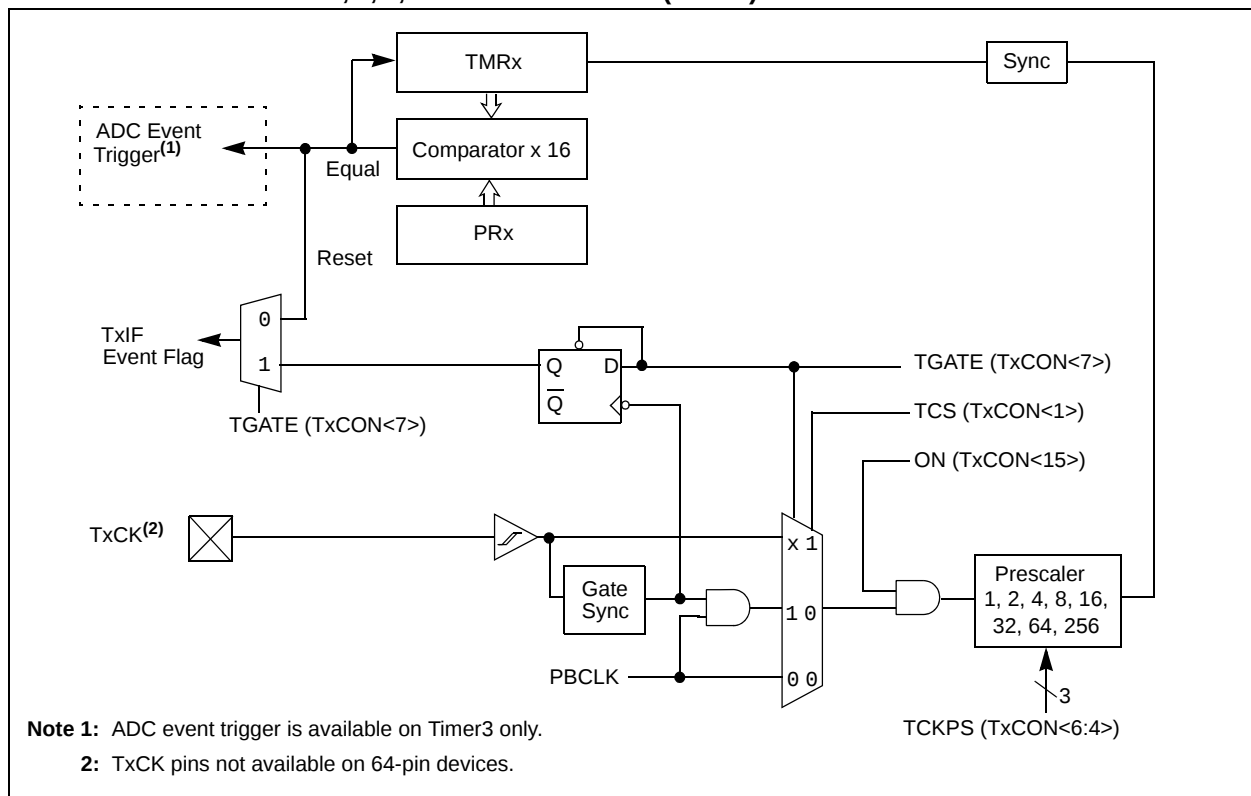
- Synchronous Internal 32-bit Timer
- Synchronous Internal 32-bit Gated Timer
- Synchronous External 32-bit Timer

Note: Throughout this chapter, references to registers TxCON, TMRx and PRx use 'x' to represent Timer2 through 5 in 16-bit modes. In 32-bit modes, 'x' represents Timer2 or 4; 'y' represents Timer3 or 5.

14.1 Additional Supported Features

- Selectable clock prescaler
- Timers operational during CPU Idle
- Time base for input capture and output compare modules (Timer2 and Timer3 only)
- ADC event trigger (Timer3 only)
- Fast bit manipulation using CLR, SET and INV registers

FIGURE 14-1: TIMER2, 3, 4, 5 BLOCK DIAGRAM (16-BIT)



PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

NOTES:

25.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. “Power-Saving Features”** (DS61130) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

This section describes power-saving for the PIC32MX3XX/4XX. The PIC32MX devices offer a total of nine methods and modes that are organized into two categories that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

25.1 Power-Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK, and by individually disabling modules. These methods are grouped into the following modes:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers.
- LPRC Run mode: the CPU is clocked from the LPRC clock source.
- Sosc Run mode: the CPU is clocked from the Sosc clock source.
- Peripheral Bus Scaling mode: peripherals are clocked at programmable fraction of the CPU clock (SYSCLK).

25.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which halt the clock to the CPU. These modes operate with all clock sources, as listed below:

- Posc Idle Mode: the system clock is derived from the Posc. The system clock source continues to operate.
Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle Mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- Sosc Idle Mode: the system clock is derived from the Sosc. Peripherals continue to operate, but can optionally be individually disabled.

- LPRC Idle Mode: the system clock is derived from the LPRC.

Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.

- Sleep Mode: the CPU, the system clock source, and any peripherals that operate from the system clock source, are halted.

Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

25.3 Power-Saving Operation

The purpose of all power-saving is to reduce power consumption by reducing the device clock frequency. To achieve this, low-frequency clock sources can be selected. In addition, the peripherals and CPU can be halted or disabled to further reduce power consumption.

25.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device Power-Saving operating modes. The CPU and most peripherals are halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep mode.

Sleep mode includes the following characteristics:

- The CPU is halted.
- The system clock source is typically shut down. See **Section 25.3.2 “Idle Mode”** for specific information.
- There can be a wake-up delay based on the oscillator selection.
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode.
- The BOR circuit, if enabled, remains operative during Sleep mode.
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode.
- Some peripherals can continue to operate in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator, e.g., RTCC and Timer 1.
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep.
- The USB module can override the disabling of the Posc or FRC. Refer to **Section 11.0 “USB On-The-Go (OTG)”** for specific details.
- Some modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption.

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB C Compiler for Various Device Families
 - HI-TECH C for Various Device Families
 - MPASM™ Assembler
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
 - MPLAB ICD 3
 - PICKit™ 3 Debug Express
- Device Programmers
 - PICKit™ 2 Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - In-Circuit Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (C or assembly)
 - Mixed C and assembly
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY⁽³⁾

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Program Flash Memory							
D130	EP	Cell Endurance	1000	—	—	E/W	—
D131	VPR	VDD for Read	V _{MIN}	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
D136	TWW	Word Write Cycle Time	20	—	40	μs	—
	TRW	Row Write Cycle Time ⁽²⁾ (128 words per row)	3	4.5	—	ms	—
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
D138	TCE	Chip Erase Cycle Time	80	—	—	ms	—
	LVDstartup	Flash LVD Delay	—	—	6	μs	—

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the “PIC32MX Flash Programming Specification” (DS61145) for operating conditions during programming and erase cycles.

TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp		
	Required Flash wait states	SYSCLK	Units
0 Wait State	0 to 30	MHz	—
1 Wait State	31 to 60		
2 Wait States	61 to 80		

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

PIC32MX3XX/4XX

FIGURE 29-5: EXTERNAL RESET TIMING CHARACTERISTICS

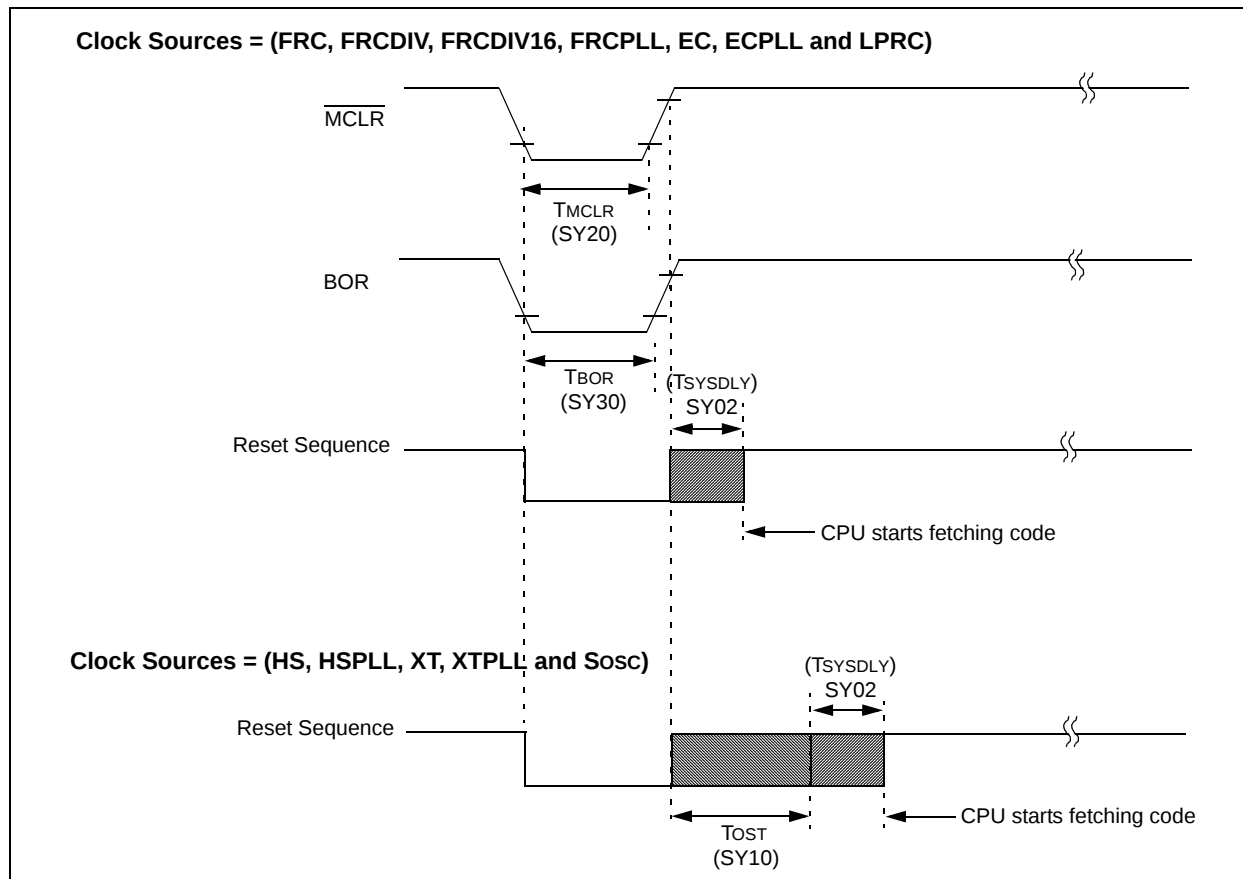


TABLE 29-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	-40°C to +85°C
SY01	TPWRT	Power-up Period External Vcore Applied (Power-Up-Timer Active)	48	64	80	ms	-40°C to +85°C
SY02	TSYSDLY	System Delay Period: Time required to reload Device Configuration Fuses plus SYSCLK delay before first instruction is fetched.	—	1 μs + 8 SYSCLK cycles	—	—	-40°C to +85°C
SY20	TMCLR	MCLR Pulse Width (low)	—	2	—	μs	-40°C to +85°C
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	-40°C to +85°C

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

PIC32MX3XX/4XX

FIGURE 29-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS

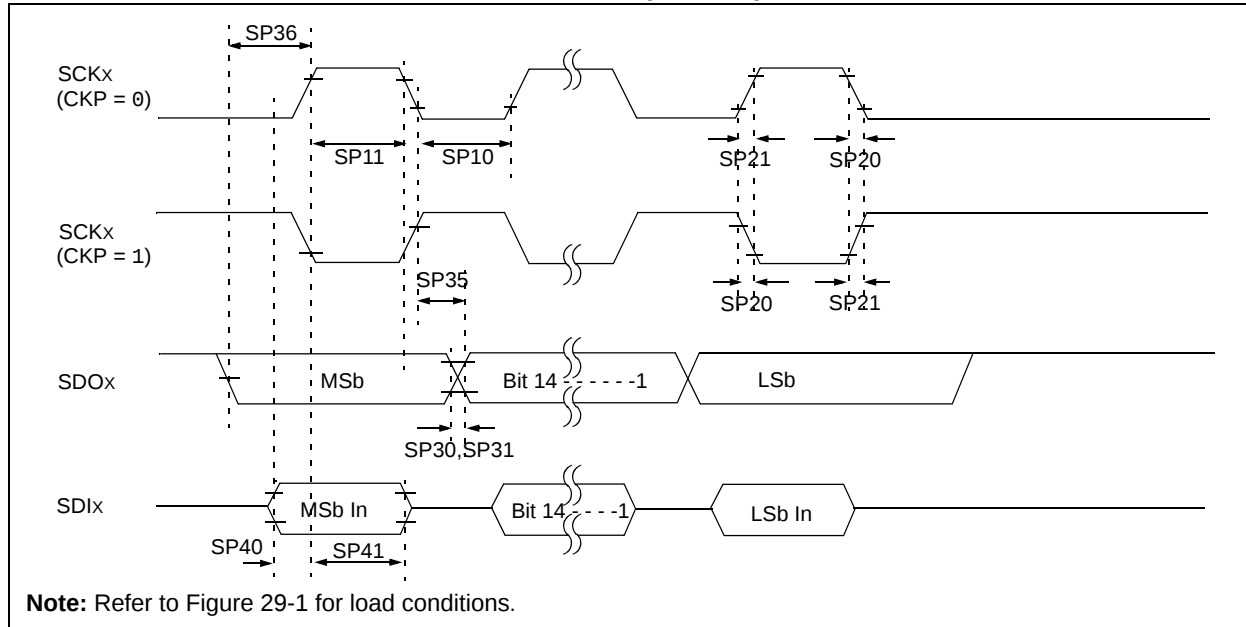


TABLE 29-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP10	TsCL	SCKx Output Low Time ⁽³⁾	Tsck/2	—	—	ns	—
SP11	TsCH	SCKx Output High Time ⁽³⁾	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP30	TdOF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdOR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	TsCH2doV, TsCL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2sCL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2sCH, TdiV2sCL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TsCH2diL, TsCL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 29-34: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 2.5	—	Lesser of VDD + 0.3 or 3.6	V	—
AD02	AVSS	Module VSS Supply	VSS	—	VSS + 0.3	V	—
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.0	—	AVDD	V	(Note 1)
AD05a			2.5	—	3.6	V	VREFH = AVDD (Note 3)
AD06	VREFL	Reference Voltage Low	AVSS	—	VREFH – 2.0	V	(Note 1)
AD07	VREF	Absolute Reference Voltage (VREFH – VREFL)	2.0	—	AVDD	V	(Note 3)
AD08	IREF	Current Drain	—	250 —	400 3	μA μA	ADC operating ADC off
Analog Input							
AD12	VINH-VINL	Full-Scale Input Span	VREFL	—	VREFH	V	—
AD13	VINL	Absolute VINL Input Voltage	AVSS – 0.3	—	AVDD/2	V	—
AD14	VIN	Absolute Input Voltage	AVSS – 0.3	—	AVDD + 0.3	V	—
AD15	—	Leakage Current	—	±0.001	±0.610	μA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V Source Impedance = 10KΩ
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	5K	Ω	(Note 1)
ADC Accuracy – Measurements with External VREF+/VREF-							
AD20c	Nr	Resolution	10 data bits			bits	—
AD21c	INL	Integral Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD22c	DNL	Differential Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V (Note 2)
AD23c	GERR	Gain Error	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD24n	EOFF	Offset Error	—	—	<±1	LSb	VINL = AVSS = 0V, AVDD = 3.3V
AD25c	—	Monotonicity	—	—	—	—	Guaranteed

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

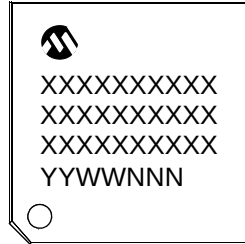
3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with 1 kHz sinewave.

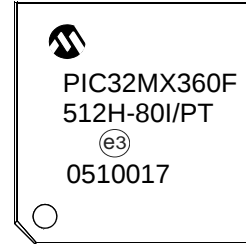
30.0 PACKAGING INFORMATION

30.1 Package Marking Information

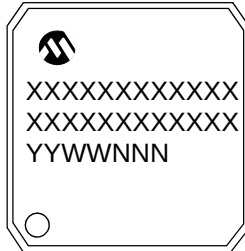
64-Lead TQFP (10x10x1 mm)



Example



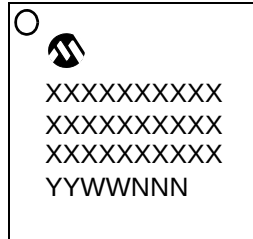
100-Lead TQFP (12x12x1 mm)



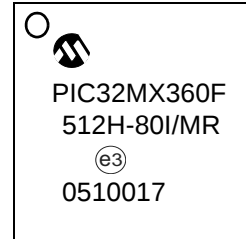
Example



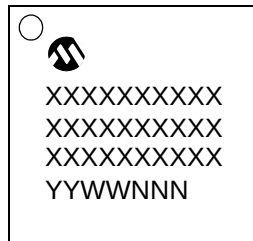
64-Lead QFN (9x9x0.9 mm)



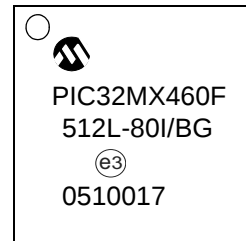
Example



121-Lead XBGA (10x10x1.1 mm)



Example

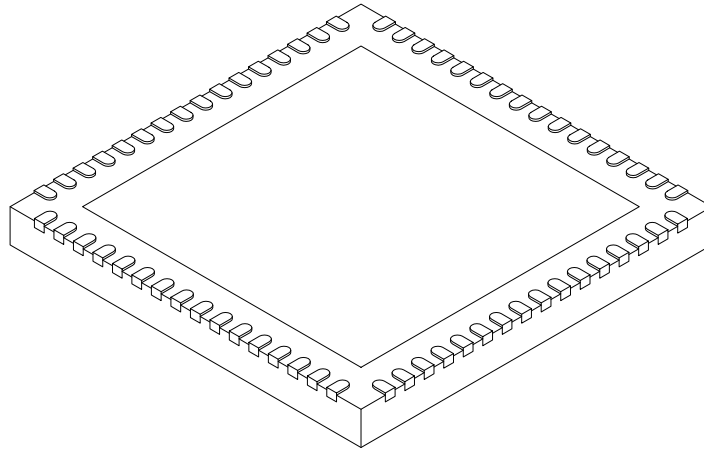


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	*	Pb-free JEDEC designator for Matte Tin (Sn)
		This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	7.05	7.15	7.50
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	7.05	7.15	7.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

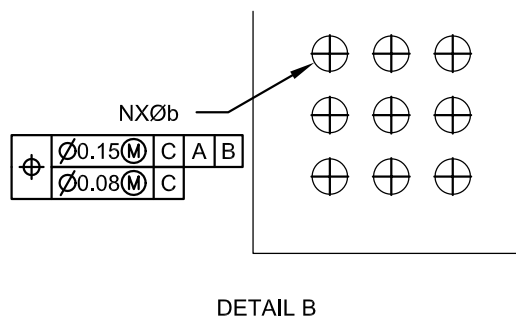
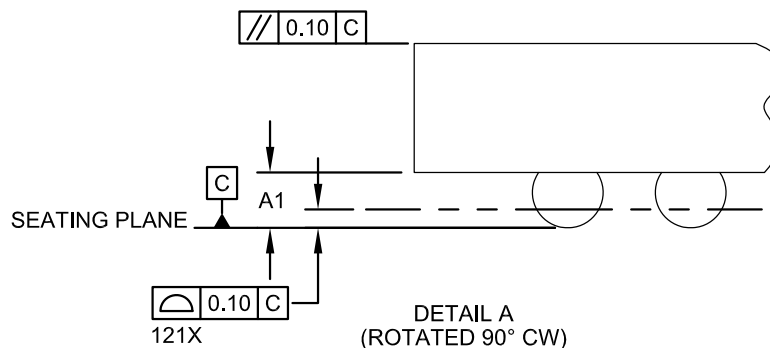
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149C Sheet 2 of 2

PIC32MX3XX/4XX

121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Contacts	N	121		
Contact Pitch	e	0.80 BSC		
Overall Height	A	1.00	1.10	1.20
Standoff	A1	0.25	0.30	0.35
Molded Package Thickness	A2	0.55	0.60	0.65
Overall Width	E	10.00 BSC		
Array Width	E1	8.00 BSC		
Overall Length	D	10.00 BSC		
Array Length	D1	8.00 BSC		
Contact Diameter	b	0.40 TYP		

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
- The outer rows and columns of balls are located with respect to datums A and B.

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